

ZXTP19020DFF

20V PNP MEDIUM POWER TRANSISTOR IN SOT23F

Features

- BV_{CEO} > -20V
- BV_{ECO} > -4V
- I_C = -5.5A Continuous Collector Current
- I_{CM} = -15A Peak Current
- Guaranteed Gain at I_C of -10A
- V_{CE(SAT)} < -44mV @ -1A
- R_{CE(SAT)} = 26mΩ
- 1.5W Power Dissipation
- Complementary PNP Type: ZXTN19020DFF
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

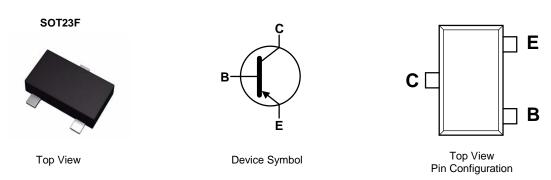
Advanced process capability and package design have been used to maximize the power handling and performance of this small outline transistor. The compact size and ratings of this device make it ideally suited to applications where space is at a premium.

Mechanical Data

- Case: SOT23F
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 [®]
- Weight: 0.012 grams (Approximate)

Applications

- MOSFET and IGBT Gate Driving
- Power Switches
- Motor Control



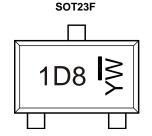
Ordering Information (Note 4)

I	Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
	ZXTP19020DFFTA	AEC-Q101	1D8	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



1D8 = Product Type Marking Code
YW = Date Code Marking
Y = Year: 0~9
W = Week: A~Z: 1~26
a~z: 27~52
z represents 52 & 53 week



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-25	V
Collector-Emitter Voltage (Base Open)	V _{CEO}	-20	V
Emitter – Collector Voltage (Reverse Blocking)	V _{ECO}	-4	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	Ic	-5.5	Α
Peak Pulse Current	I _{CM}	-15	Α
Base Current	I _B	-1	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 5)		0.84 6.72		
Power Dissipation	(Note 6)	P _D	1.34 10.72	W mW/°C	
Linear Derating Factor	(Note 7)		1.50 12.0		
	(Note 8)		2.0 16.0		
	(Note 5)		149		
The word Desistance I treation to Austriant	(Note 6)		93	90044	
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	83	°C/W	
	(Note 8)		60		
Thermal Resistance, Junction to Lead (Note 9)		$R_{\theta JL}$	43.8	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

ESD Ratings (Note 10)

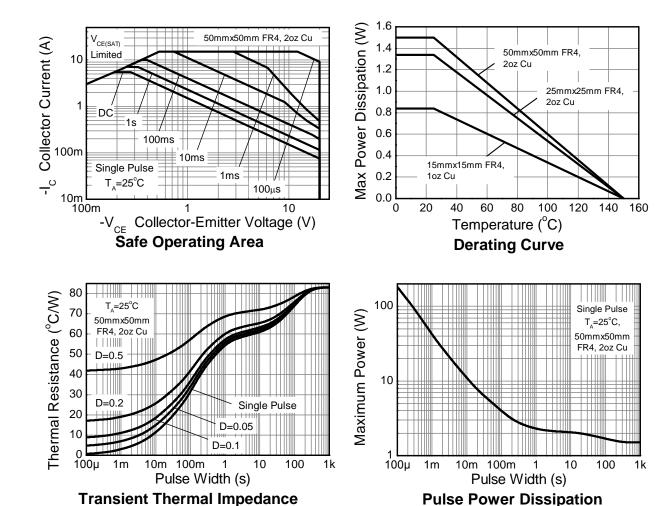
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge – Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge – Machine Model	ESD MM	400	V	С

Notes:

- 5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.
- 7. Same as Note 5, except the device is mounted on 50mm x 50mm 2oz copper.
- 8. Same as Note 7, whilst measured at t < 5 seconds.
- 9. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





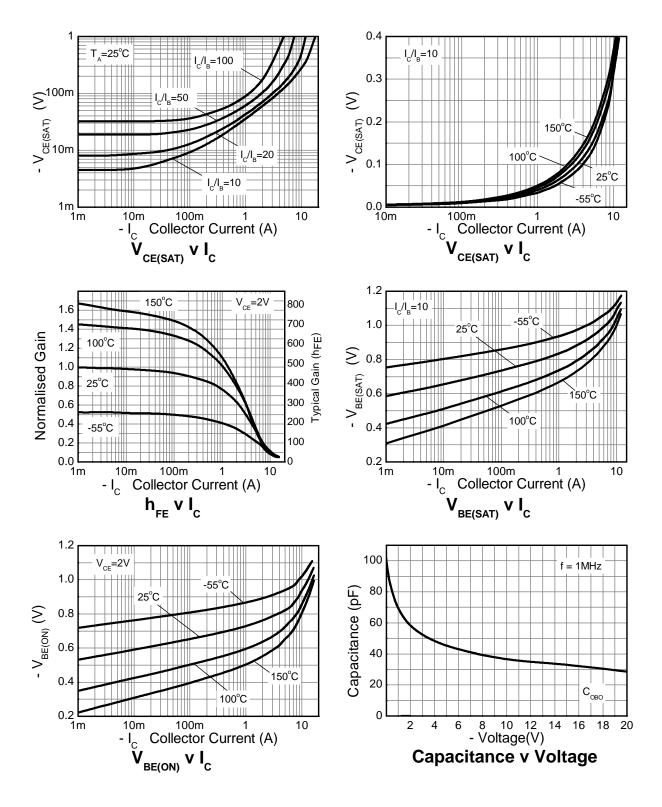
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-25	-55	_	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Base Open) (Note 11)	BV _{CEO}	-20	-50	_	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.6	_	V	I _E = -100μA
Emitter – Collector Breakdown Voltage (Reverse Blocking)	BV _{ECX}	-4	-8.6	_	V	I_E = -100μA, R_{BC} < 1k Ω , or 0.25V > V_{BC} > -0.25V
Emitter – Collector Breakdown Voltage (Base Open)	BV _{ECO}	-4	-8.6	_	V	I _E = -100μA
Collector-Base Cut-off Current	I _{CBO}	_	<-1 —	-50 -0.5	nΑ μΑ	V _{CB} = -25V V _{CB} = -25V, T _A = +100°C
Emitter-Base Cut-off Current	I _{EBO}	_	<-1	-50	nA	V _{EB} = -5.6V
ON CHARACTERISTICS (Note 11)		Т	T	Т	Г	
Static Forward Current Transfer Ratio	h _{FE}	300 200 85 25	450 310 130 50 20	900 — — — —	_	$\begin{split} & I_{C} = -0.1A, \ V_{CE} = -2V \\ & I_{C} = -2A, \ V_{CE} = -2V \\ & I_{C} = -5.5A, \ V_{CE} = -2V \\ & I_{C} = -10A, \ V_{CE} = -2V \\ & I_{C} = -15A, \ V_{CE} = -2V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-37 -90 -105 -160 -145	-44 -125 -140 -210 -175	mV	I_C = -1A, I_B = -100mA I_C = -1A, I_B = -10mA I_C = -2A, I_B = -40mA I_C = -5A, I_B = -250mA I_C = -5.5A, I_B = -550mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	_	-975	-1050	mV	I _C = -5.5A, I _B = -550mA
Base-Emitter On Voltage	V _{BE(ON)}	_	-830	-900	mV	$I_C = -5.5A$, $V_{CE} = -2V$
SMALL SIGNAL CHARACTERISTICS						•
Transition Frequency	f⊤	_	176	_	MHz	$I_C = -50$ mA, $V_{CE} = -10$ V, $f = 50$ MHz
Input Capacitance	C _{IBO}	_		400	pF	V _{EB} = -0.5V, f = 1MHz
Output Capacitance	C _{OBO}	_	36	45	pF	V _{CB} = -10V, f = 1MHz
Delay Time	t _D	_	23	_	ns	101/
Rise Time	t _R	_	18	_	ns	$V_{CC} = -10V$,
Storage Time	t _S	_	266	_	ns	$I_{C} = -1A,$ $I_{B1} = -I_{B2} = 50mA$
Fall Time	t _F	_	50	_	ns	7 IB1 = - IB2 = DUITIA

Note: 11. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

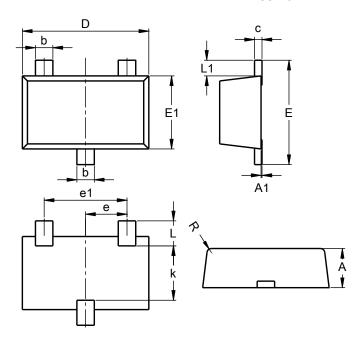




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23F

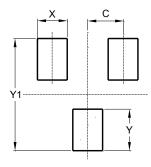


SOT23F						
Dim	Min Max Typ					
Α	0.80	1.00	0.90			
A1	0.00	0.10	0.01			
b	0.35	0.50	0.44			
С	0.10	0.20	0.16			
D	2.80 3.00 2.90					
е	0.95 REF					
e1	1.90 REF					
Е	2.30	2.50	2.40			
E1	1.50	1.70	1.65			
k	1.20	-	-			
L	0.30	0.65	0.50			
L1	0.30	0.50	0.40			
R	0.05	0.15	-			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23F



Dimensions	Value (in mm)		
С	0.95		
X	0.80		
Υ	1.110		
Y1	3.000		



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